

EAST Search History

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|--------|--|---|------------------|---------|------------------|
| S12 7 | 8 | S126 and (@ad < "20030211") | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/10 18:16 |
| S12 8 | 3434 | ((438/108) or (438/116) or (438/123) or (438/124)).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/12/23 18:46 |
| S12 9 | 2 | "5869883".pn. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/10 17:09 |
| S13 0 | 217667 | flip | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/10 17:09 |
| S13 1 | 0 | S129 and S130 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/10 17:09 |
| S13 2 | 27237 | ball adj grid adj array bga ball-grid adj array | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/10 17:10 |
| S13 3 | 31198 | flip adj chip flip-chip | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/10 17:10 |
| S13 4 | 66300 | lead\$4 adj frame lead\$4-frame | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/10 17:12 |
| S13 5 | 6565 | premold\$5 pre adj mold\$5 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/10 20:49 |

EAST Search History

| | | | | | | |
|----------|--------|--|---|----|----|------------------|
| S13 6 | 194 | S135 same S134 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/10 17:12 |
| S13 7 | 39 | S136 and (S132 S133) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/10 17:13 |
| S13 8 | 27 | S137 and (@ad < "20030211") | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/10 19:34 |
| S13 9 | 2 | "20020047501".pn. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/10 18:17 |
| S14 0 | 242233 | mosfet or (metal adj (oxide insulat\$4) adj semiconducor adj (fet or field)) or pmos or cmos or nmos or misfet | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/10 18:17 |
| S14 1 | 4594 | verti\$8 near S140 vmosfet vmos vcmos v?mos\$4 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/10 18:17 |
| S14 2 | 0 | S139 and (S140 S141) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/10 18:17 |
| S14 3 | 14521 | source near2 lead | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/10 18:29 |
| S14 4 | 24353 | gate near2 (lead wire wiring) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/10 18:30 |
| S14 5 | 41025 | source near2 (lead wire wiring pad ball) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/10 18:31 |

EAST Search History

| | | | | | | |
|----------|-------|--|---|----|----|------------------|
| S14 6 | 31054 | gate near2 (lead wire wiring pad ball) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/10 18:31 |
| S14 7 | 25 | S141 and S145 and S146 and S133 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/10 18:31 |
| S14 8 | 8 | S147 and (@ad < "20030211") | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/10 19:23 |
| S14 9 | 0 | S139 and (reflow\$4) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/10 19:25 |
| S15 0 | 2 | "6392290".pn. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/10 19:25 |
| S15 1 | 1 | S150 and (reflow\$4) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/10 19:26 |
| S15 2 | 2 | S150 and (solder ball bump reflow\$4) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/10 19:41 |
| S15 3 | 1 | S150 and (solder ball bump reflow\$4) same (heat\$4 thermal\$4) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/10 19:33 |
| S15 4 | 9 | S133 with S134 with (reflow\$4) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/10 19:34 |
| S15 5 | 6 | S154 and (@ad < "20030211") | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/10 19:41 |

EAST Search History

| | | | | | | |
|----------|---------|--|---|----|----|------------------|
| S15 6 | 6 | (solder ball bump) with reflow\$4 with S134 with S133 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/10 19:42 |
| S15 7 | 4 | S156 and (@ad < "20030211") | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/10 19:42 |
| S15 8 | 7 | (solder ball bump) near4 S134 with reflow\$4 same S133 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/10 19:54 |
| S15 9 | 5 | S158 and (@ad < "20030211") | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/10 19:58 |
| S16 0 | 270 | (solder ball bump) near2 (form\$4 attach\$4 deposit\$4) near2 S134 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/10 19:56 |
| S16 1 | 1613572 | ic die dice chip | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/10 19:55 |
| S16 2 | 6700 | (solder ball bump) near2 (form\$4 attach\$4 deposit\$4) near2 S161 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/10 19:56 |
| S16 3 | 2626 | S161 and S162 and reflow\$4 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/10 19:56 |
| S16 4 | 1028 | S161 same S162 same reflow\$4 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/10 19:57 |
| S16 5 | 186 | (solder ball bump) near2 (form\$4 deposit\$4) near2 S134 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/10 20:15 |

EAST Search History

| | | | | | | |
|----------|-------|--|---|----|----|------------------|
| S16 6 | 4979 | (solder ball bump) near2 (form\$4 deposit\$4) near2 S161 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/10 20:15 |
| S16 7 | 0 | S165 same S166 same reflow\$4 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/10 19:58 |
| S16 8 | 9 | S165 and S166 and reflow\$4 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/10 19:58 |
| S16 9 | 6 | S168 and (@ad < "20030211") | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/10 20:04 |
| S17 0 | 31204 | S165 same reflow\$4 S133 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/10 20:03 |
| S17 1 | 0 | S165 with reflow\$4 with S133 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/10 20:03 |
| S17 2 | 0 | S165 with reflow\$4 same S133 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/10 20:04 |
| S17 3 | 0 | S165 with reflow\$4 and S133 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/10 20:03 |
| S17 4 | 1851 | (solder ball bump) with (form\$4 deposit\$4) with S134 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/10 20:04 |
| S17 5 | 7 | S174 with reflow\$4 same S133 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/10 20:04 |

EAST Search History

| | | | | | | |
|----------|------|--|---|----|----|------------------|
| S17 6 | 5 | S175 and (@ad < "20030211") | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/10 20:16 |
| S17 7 | 2776 | (solder ball bump) near2 (form\$4 deposit\$4) near2 (S134 board pcb) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/10 20:15 |
| S17 8 | 201 | S177 same S174 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/10 20:16 |
| S17 9 | 13 | S177 same S174 same reflow\$4 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/10 20:16 |
| S18 0 | 3 | S179 and (@ad < "20030211") | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/10 20:16 |
| S18 1 | 6565 | premold\$5 pre adj mold\$5 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/10 20:49 |
| S18 2 | 1 | S139 and S135 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/04/10 20:49 |